ABSTRACT

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH SHIELD

An integrated circuit package system includes: forming a first lead and a second lead; connecting an integrated circuit die with the first lead; forming an encapsulation over the integrated circuit die, the first lead, and the second lead with a portion of a top side of the second lead exposed; and forming a shield over the encapsulation, the first lead, and the second lead with the shield not in contact with the first lead. (Fig. 2)